

IN THE CLAIMS

1. (Currently Amended) A semiconductor package comprising a lead-free solder having an alpha flux of less than 0.0005 cts/cm²/hr.
2. (Currently Amended) The semiconductor package of claim 1 wherein the lead-free solder predominately comprises Ag, Bi, Cu, In[[,Pb]] or Sn.
3. (Original) The semiconductor package of claim 1 wherein the solder predominately comprises Ag.
4. (Original) The semiconductor package of claim 1 wherein the solder predominately comprises Sn.

Claims 5-6: Canceled.

7. (Previously Presented) The semiconductor package of claim 1 wherein the solder predominately comprises Bi, Cu or In.
8. (Previously Presented) The semiconductor package of claim 1 wherein the solder has an alpha flux of less than 0.0002 cts/cm²/hr.
9. (Previously Presented) The semiconductor package of claim 1 wherein the solder has an alpha flux of less than 0.0001 cts/cm²/hr.

Claims 10-29: Canceled.